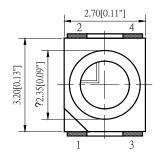
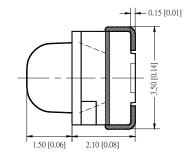
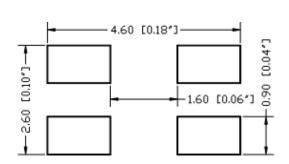


SPECIFICATION CSPD1311B3C

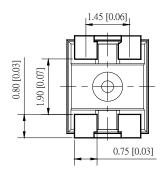
PACKAGE OUTLINES

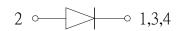






RECOMMENDED PAD LAYOUT





Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSPD1311B3C	InGaN	Blue	Water Clear	30°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 10 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Toot Condition	Value			Llmit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 30mA	800	1450	-	mcd
Forward Voltage	VF	IF = 30mA	-	3.1	3.7	V
Reverse Leakage Current	lR	VR = 5V	1	10	-	μΑ
Viewing Angle at 50% lv	201/2	IF = 30mA	-	30	-	Deg
Peak Wavelength	λР	IF = 30mA	-	460	-	nm
Dominant Wavelength	λD	IF = 30mA	460	465	470	nm

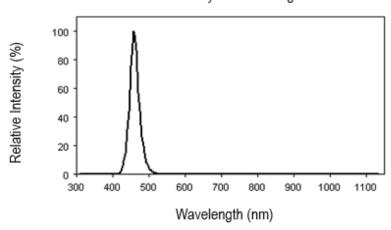
^{*}Tolerance of viewing angle: -10 / +5 deg.



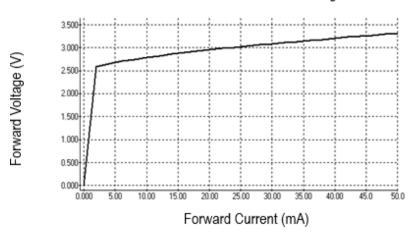


OPTICAL CHARACTERISTIC CURVES

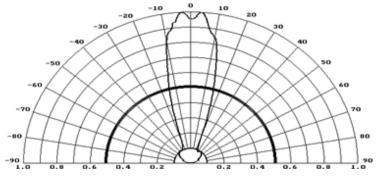
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

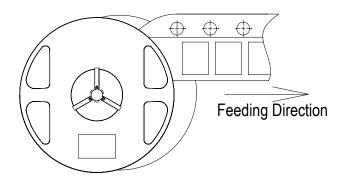


RoHS Compliant

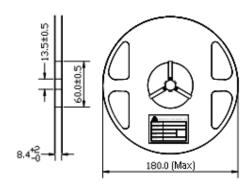


PACKAGING SPECIFICATION

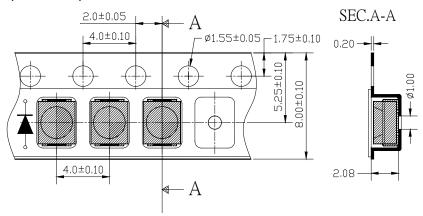
Feeding Direction



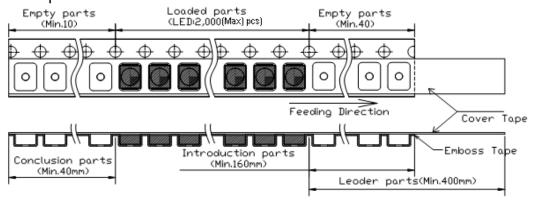
Dimensions of Reel (Unit: mm



Dimensions of Tape (Unit: mm)



Arrangement of Tape



Notes:

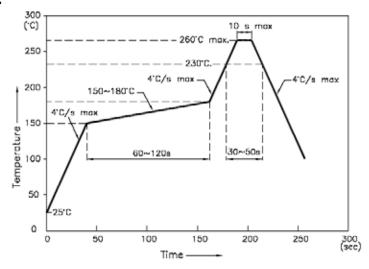
- 1. Empty component pockets are sealed with top cover tape.
- 2. The maximum number of missing lamp is two.
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 2,000 pcs/Reel





SOLDERING CONDITIONS

REFLOW PROFILE



Notes:

- 1. We recommend reflow temperature 245°C (± 5 °C). The maximum soldering temperature should be limited to 260°C.
- 2. Do not cause stress to epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process should be 2 times or less.
- Soldering Iron

Basic spec is \leq 5 sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of device should be under 230°C.

Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of the iron cannot touch copper foil.
- 3. Twin-head type is preferred

